Updates on PT Module FE Analysis

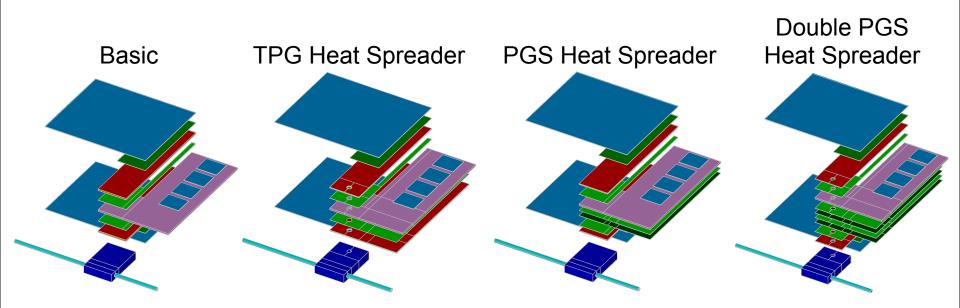




Andreas Mussgiller Tracker Upgrade Meeting 19/04/2011



Trigger Module Design Variants

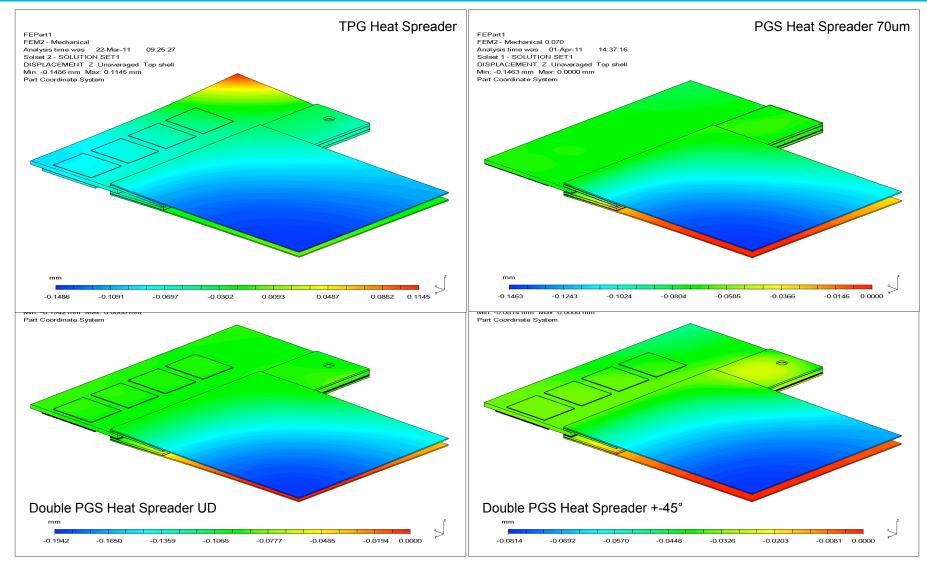


- > PGS Heat Spreader design was modelled with two different PGS layer thicknesses (70um/100um)
- Double PGS Heat Spreader design was modelled with two different CFRP support strip fiber orientations
- > Why do both sensors bend towards each other in all designs?
- > What is the effect of ,switching' on convection in the thermal calculations?





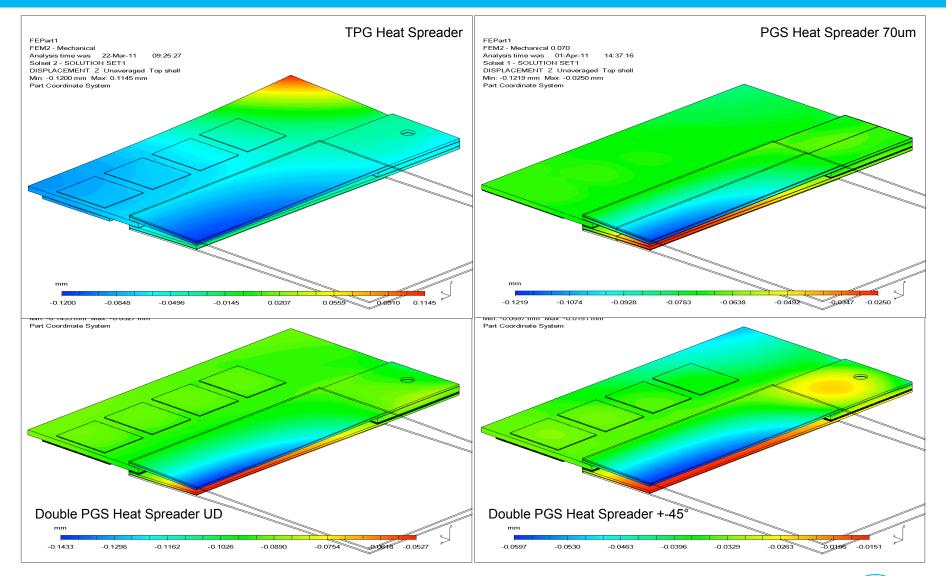
Z Displacement of Nodes







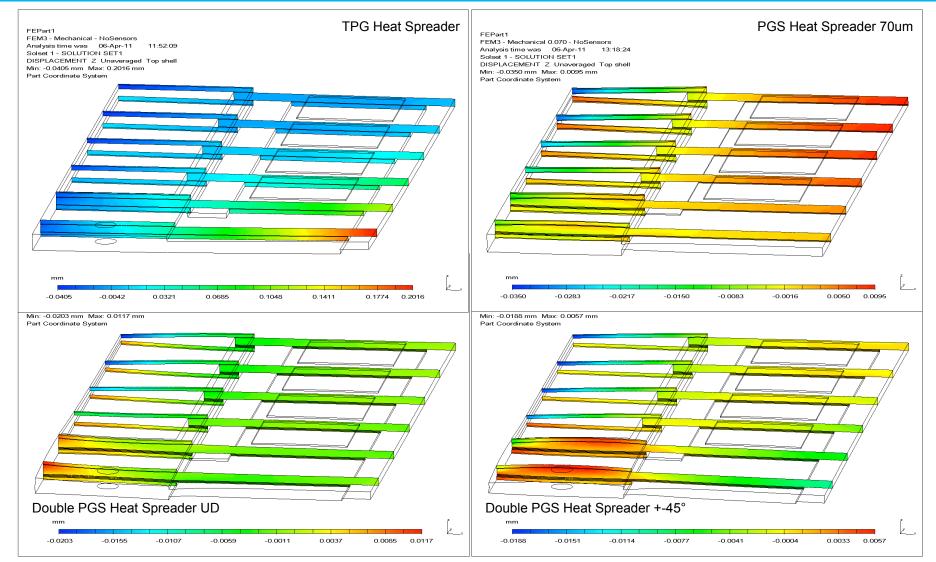
Z Displacement of Nodes - Displayed without Sensors





DFS

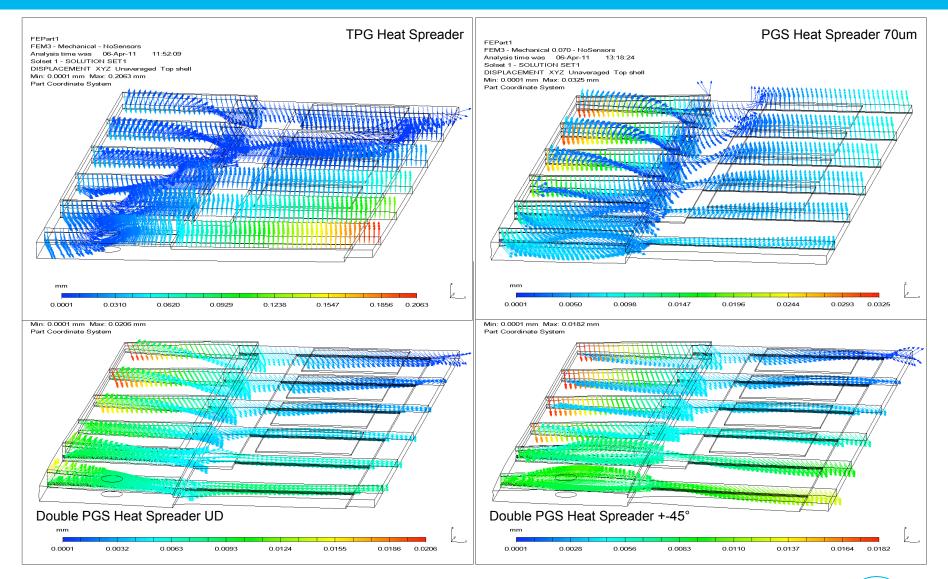
Z Displacement of Nodes - Modell without Sensors







XYZ Displacement of Nodes - Modell without Sensors





Thermal FE Analysis with Convection

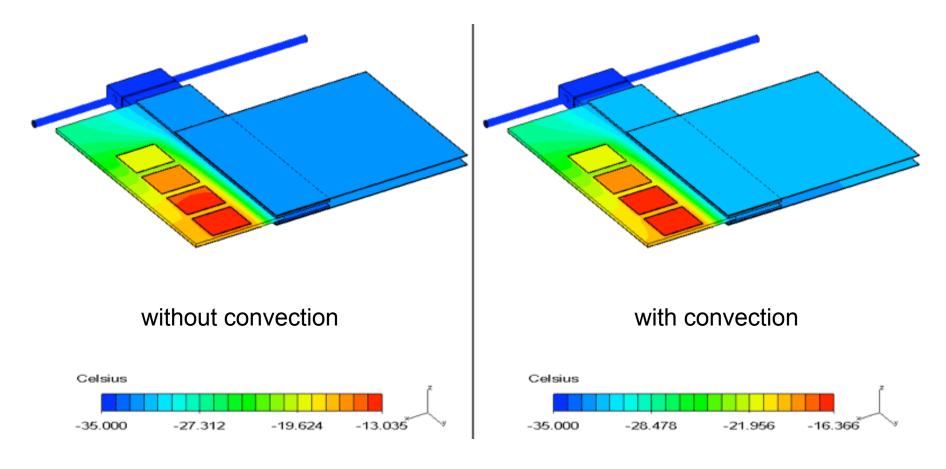
- > 100mW consumed by sensor (25mW in FE model)
- > 2W consumed by chips (125mW per chip; 500mW in FE model)
- > Heat transfer coefficient for free convection assumed to be 5W/m^2/K
- > Ambient temperature set such that heat flux to ambient is zero
 - No additional heat load or loss due to convection





PGS Heat Spreader Design (70um)

- > Ambient temperature set to -30.1°C
- > 10mW Remaining convective heat loss







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